



SOD923

Microlead ultra small surface-mounted plastic package; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOD2
Package type industry code	SOD2
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	12-4-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.75	-	0.8	0.85	mm
E	package width	0.55	-	0.6	0.65	mm
A	seated height	0.34	-	0.37	0.4	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

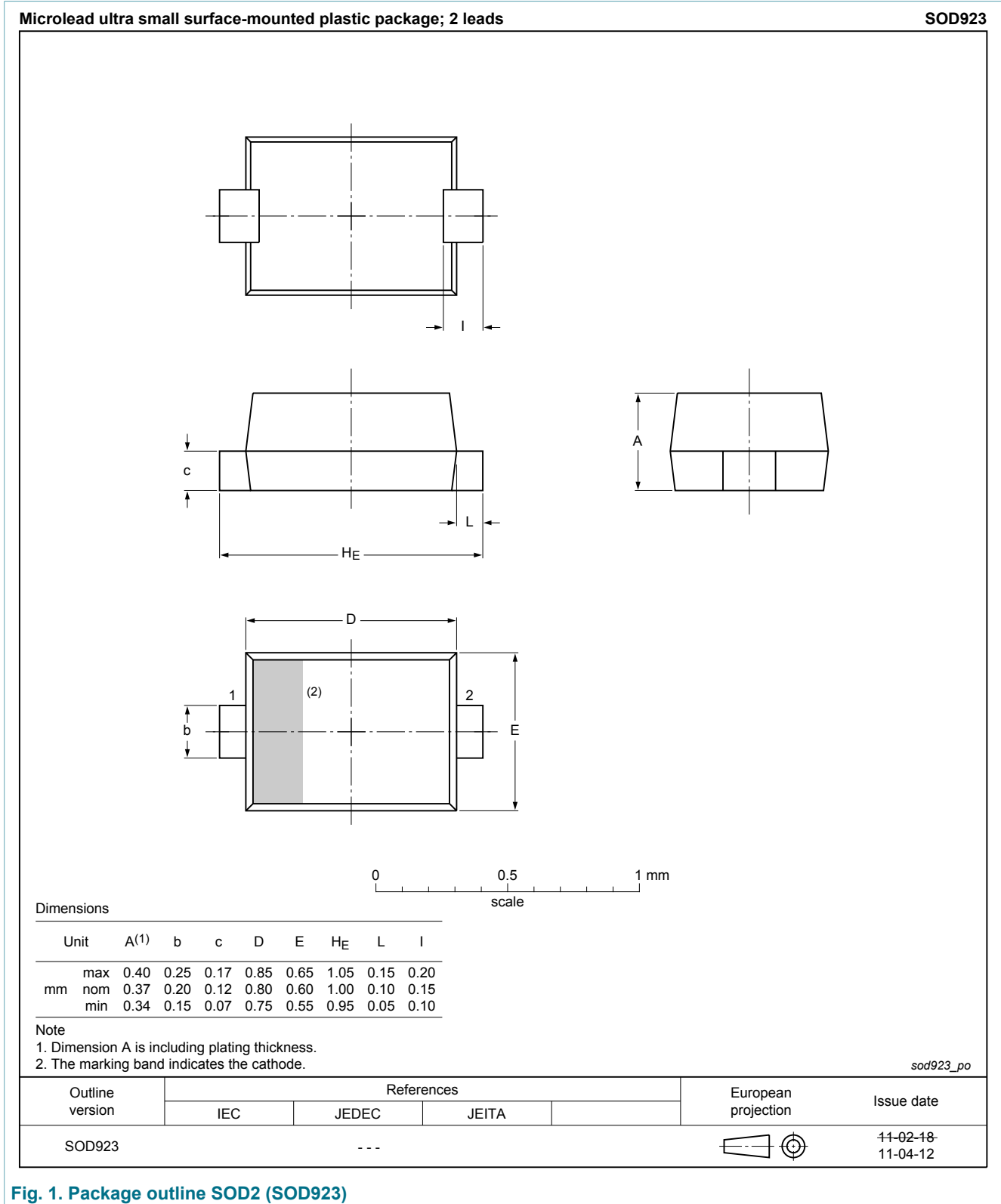


Fig. 1. Package outline SOD2 (SOD923)

3. Soldering

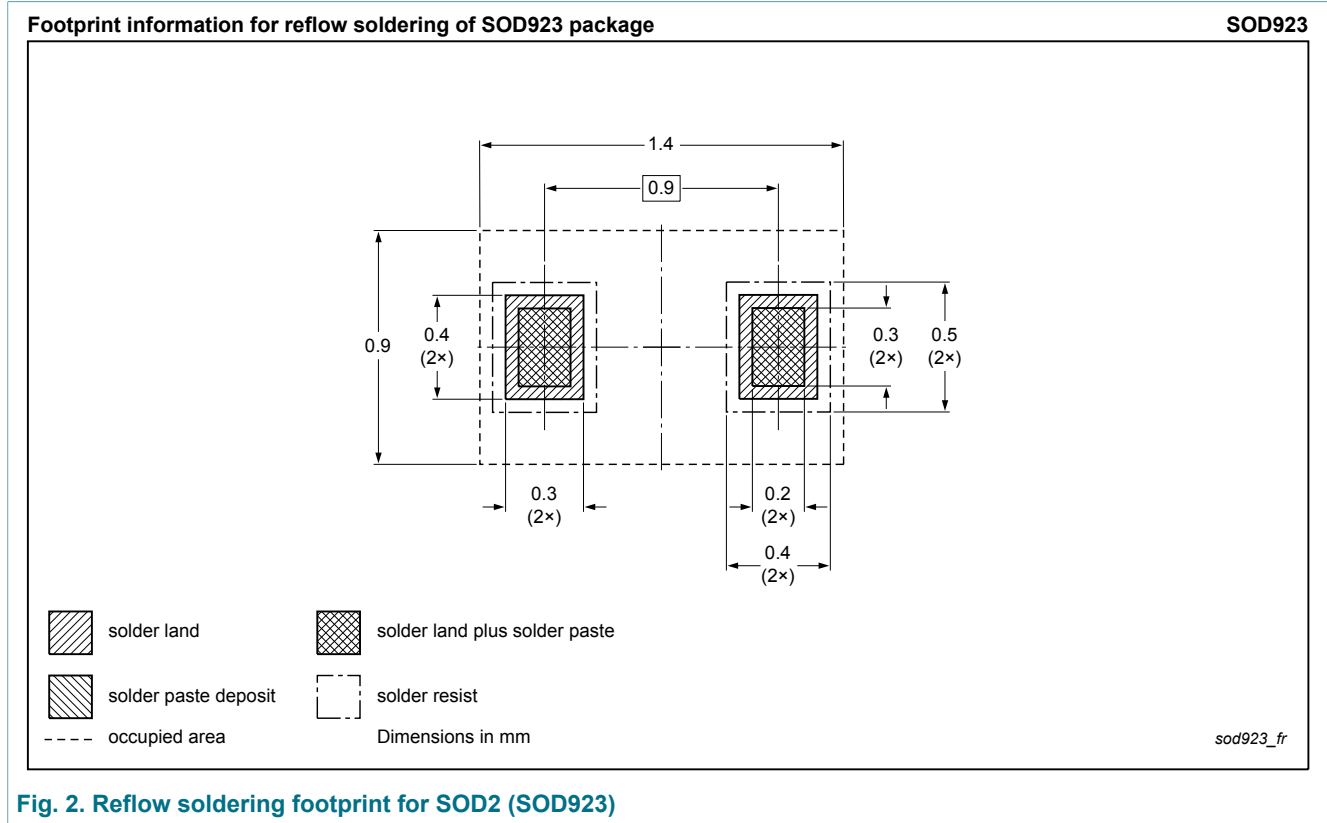


Fig. 2. Reflow soldering footprint for SOD2 (SOD923)

4. Legal information

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Date of release: 8 February 2016
